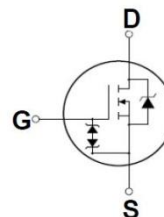
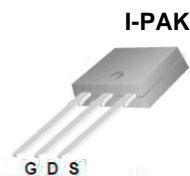


N-channel MOSFET

Features

- Low gate charge
- 100% avalanche tested
- Improved dv/dt capability
- RoHS compliant
- Halogen free package
- JEDEC Qualification

BV_{DSS}	I_D	$R_{DS(on)}$
500V	2.5A	<2.8W



Device	Package	Marking	Remark
TMD3N50Z / TMU3N50Z	D-PAK/I-PAK	TMD3N50Z / TMU3N50Z	RoHS
TMD3N50ZG / TMU3N50ZG	D-PAK/I-PAK	TMD3N50ZG / TMU3N50ZG	Halogen Free

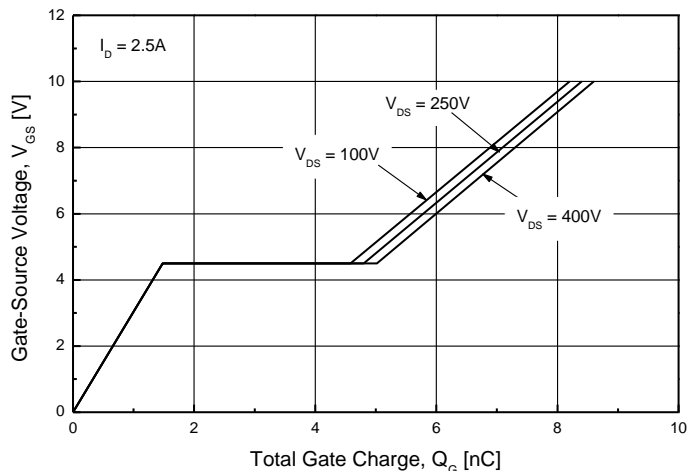
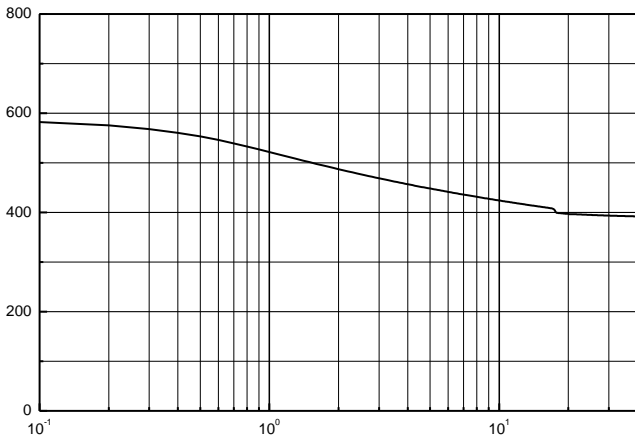
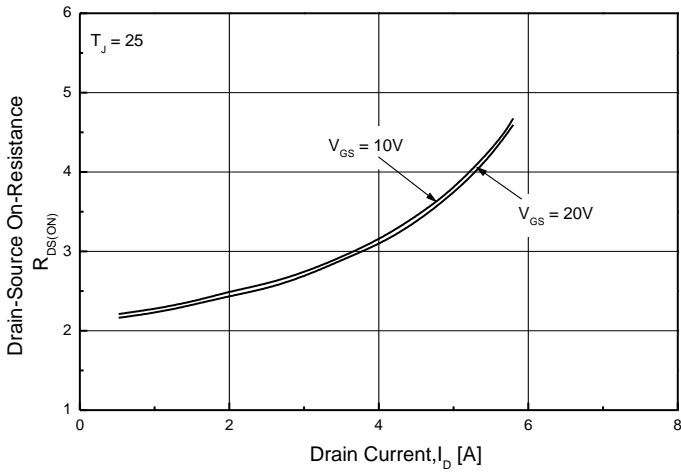
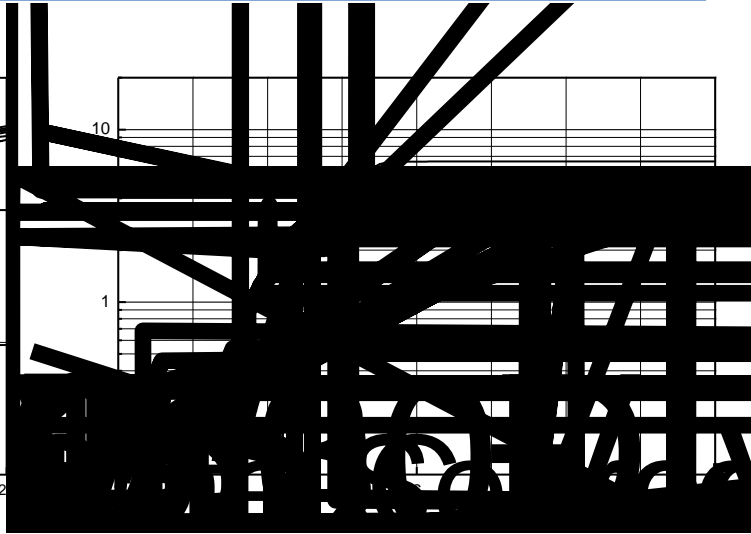
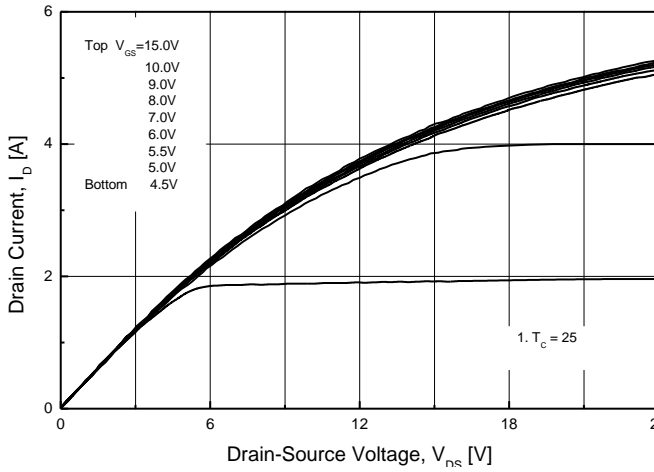
Absolute Maximum Ratings

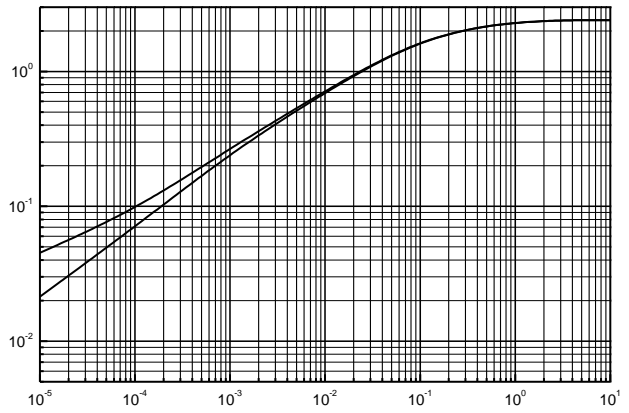
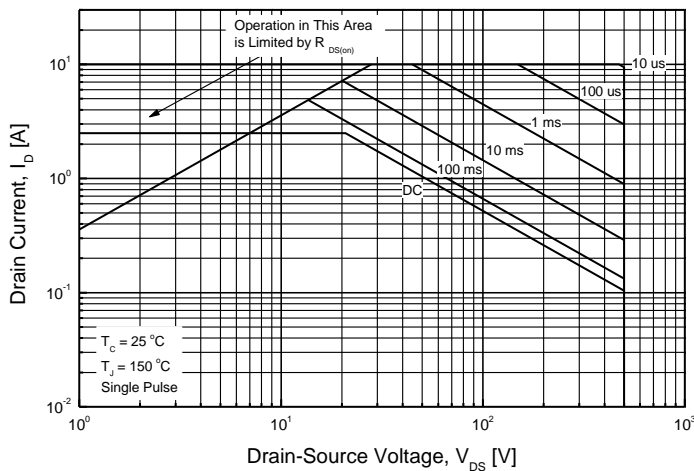
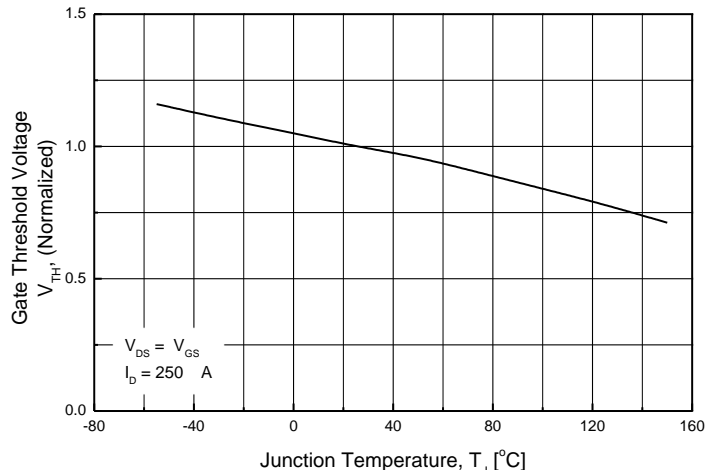
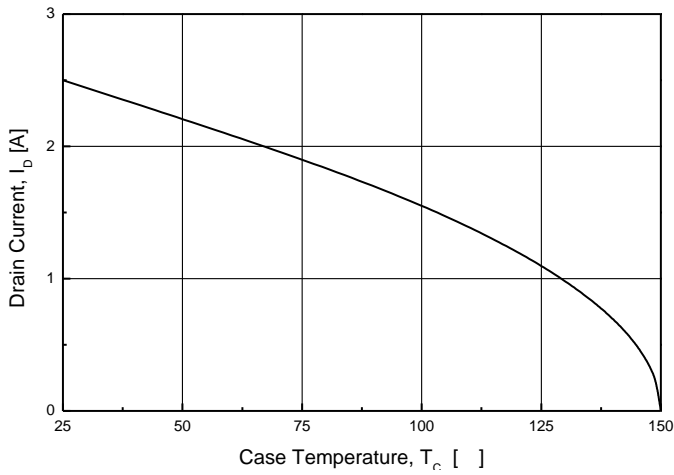
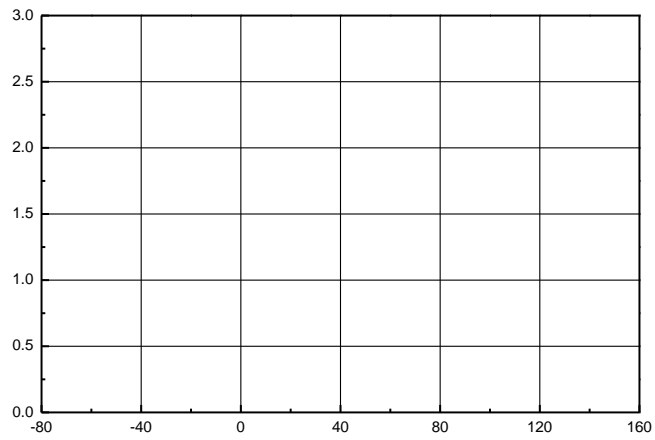
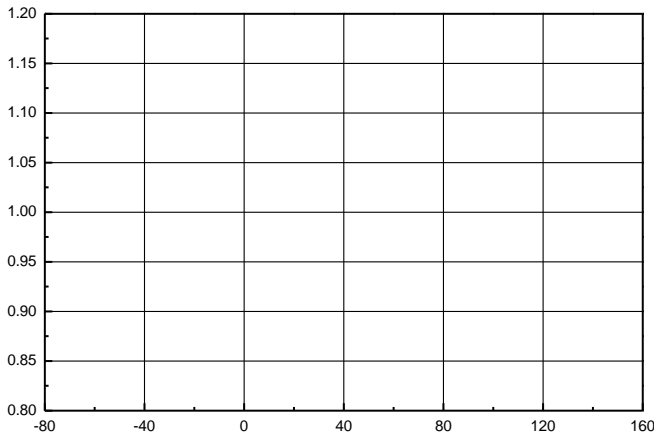
Parameter	Symbol	TMD3N50Z(G)/TMU3N50Z(G)	Unit
Drain-Source Voltage	V_{DSS}	500	V
Gate-Source Voltage	V_{GS}	30	V
Continuous Drain Current	I_D	$T_C = 25$	A
		$T_C = 100$	A
Pulsed Drain Current (Note 1)	I_{DM}	10	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	107	mJ
Repetitive Avalanche Current (Note 1)	I_{AR}	2.5	A
Repetitive Avalanche Energy (Note 1)	E_{AR}	5.2	mJ
Power Dissipation	P_D	$T_C = 25$	W
		Derate above 25	W/
Peak Diode Recovery dv/dt (Note 3)	dv/dt	4.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~150	
Maximum lead temperature for soldering purposes,	T_L	300	

* Limited only by maximum junction temperature

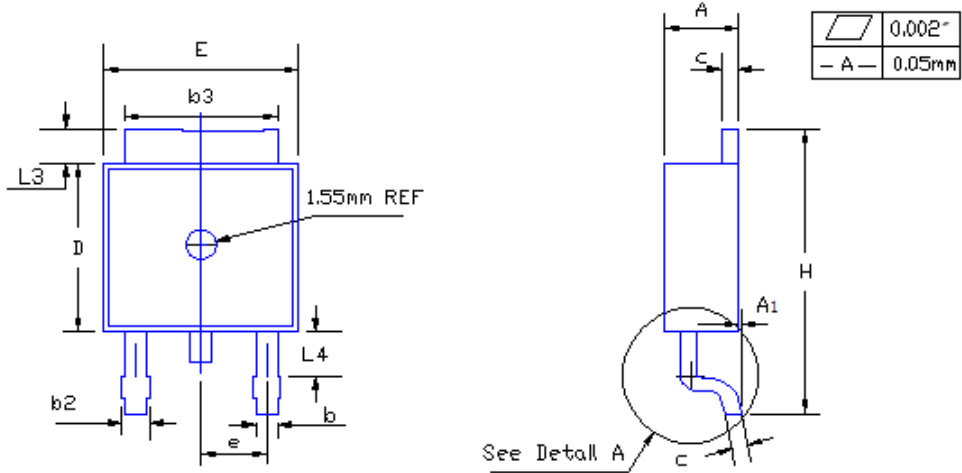
Thermal Characteristics

Parameter	Symbol	TMD3N50Z(G)/TMU3N50Z(G)	Unit
Maximum Thermal resistance, Junction-to-Case	R_{qJC}	2.4	/W
Maximum Thermal resistance, Junction-to-Ambient	R_{qJA}	110	/W





TO-252 (D-PAK) MECHANICAL DATA



SYMBOL	MILLIMETERS	
	MIN	MAX
A	2.19	2.38
A1	—	0.13
b	0.64	0.89
b2	0.84	1.14
b3	5.21	5.46
c	0.46	0.61
D	5.97	6.22
D1	5.21	—
E	6.35	6.73
E1	4.83	—
e	2.29BSC	
H	9.65	10.41
L	1.40	1.78
L2	0.51BSC	
L3	0.89	1.27
L4	0.64	1.01
Ø	0	8

TO-251 (I-PAK) MECHANICAL DATA



SYMBOL	MILLIMETERS	
	MIN	MAX
A	2.19	2.38
A1	1.04	1.23
b	0.64	0.89
b1	0.84	1.14
b2	5.23	5.48
c	0.46	0.61
D	5.91	6.28
E	6.21	6.59
e	2.28 TYP	
L	8.89	9.65
L2	0.89	1.27